

ABSTRACT

microwave package with surface mounting and  
corresponding mounting with a multilayer circuit

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The invention relates to a microwave package delimiting  
an interior volume, comprising at least:

- a Faraday cage formed by a conducting surface (1,  
5, 3e) surrounding the interior volume,
- 10 - a connection point (8a) placed outside the Faraday  
cage, the connection point being intended to be  
linked electrically to an exterior circuit,
- an input-output passing through the Faraday cage  
and linked electrically to the connection point,
- 15 - a base (3) forming a face of the package, the  
exterior surface of the base forming a mounting  
surface intended to be applied to the exterior  
circuit, the connection point being placed on the  
mounting surface, so that the connection point is  
20 placed between the Faraday cage and the exterior  
circuit when the package is mounted on the  
exterior circuit.

The invention applies to microwave packages used in the  
25 realms of avionics, telecommunications, space.

Figure 1